



Company Overview

About Rambus

Rambus delivers industry-leading chips and silicon IP for the data center and AI infrastructure. With over three decades of advanced semiconductor experience, our products and technologies address the critical bottlenecks between memory and processing to accelerate data-intensive workloads. By enabling greater bandwidth, efficiency and security across next-generation computing platforms, we make data faster and safer.

Executive Team

Luc Seraphin

President & Chief Executive Officer

Sean Fan

Executive Vice President
& Chief Operating Officer

Desmond Lynch

Senior Vice President
& Chief Financial Officer

Simon Blake-Wilson

Senior Vice President
& General Manager of Silicon IP

Cliff Burnette

Senior Vice President
& Chief Human Resources Officer

I Nong Chao

Senior Vice President,
Global Operations

Matt Jones

Senior Vice President,
Corporate Strategy

Shyam Ramachandran

Senior Vice President
& Chief Information Officer

Kit Rodgers

Senior Vice President, Technology
Partnerships & Corporate Development

Rami Sethi

Senior Vice President & General
Manager of Memory Interface Chips

John Shinn

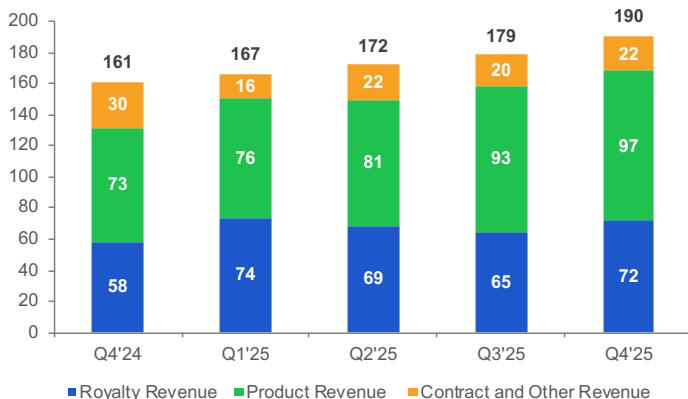
Senior Vice President
& General Counsel

Company Facts

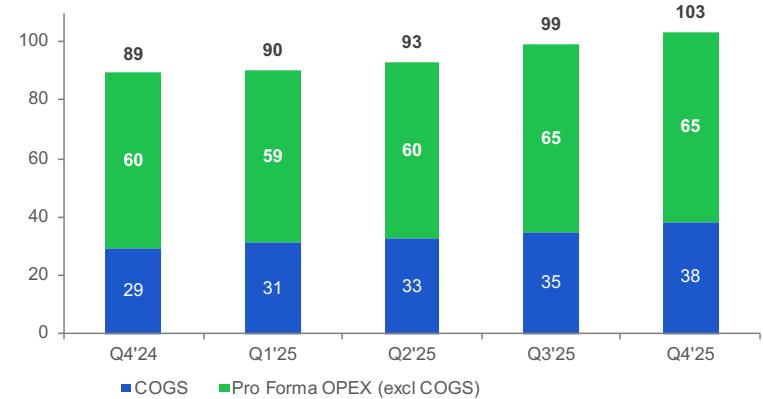
- NASDAQ: RMBS; incorporated in 1990; IPO in 1997
- Headquartered in San Jose, CA
- Operations throughout North America, Europe & Asia
- Cash from Operations:
Q4 2025: \$99.8M
2025: \$360.0M
- ~800 employees

This document contains non-GAAP financial measures. Reconciliations of these non-GAAP financial measures to the most directly comparable measures calculated in accordance with GAAP are posted on our website at rambus.com.

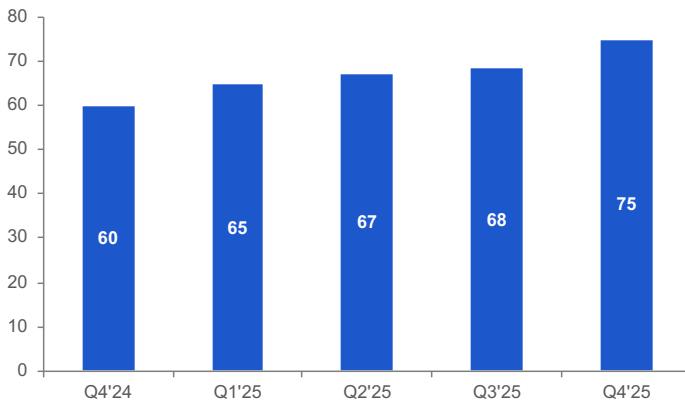
Revenue (\$M)



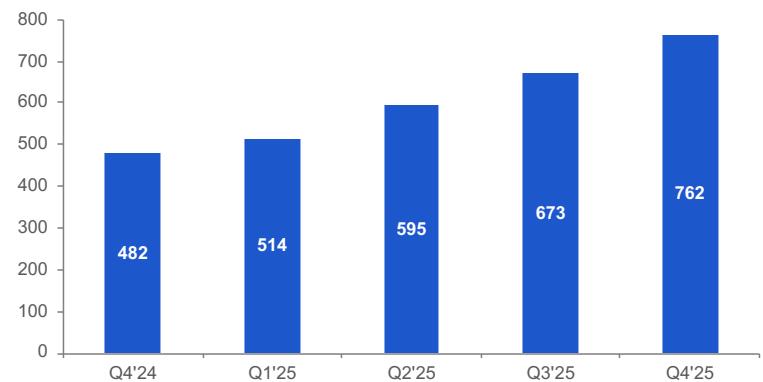
Pro Forma Expenses (\$M)



Pro Forma Net Income (\$M)



Cash and Marketable Securities (\$M)



Certain amounts may be off by \$1M due to rounding.

